

DATA SHEET

SURFACE MOUNT MULTILAYER
CERAMIC CAPACITORS

General purpose & High capacitance

Class 2, X5R

4 V TO 50 V

100 pF to 100 μ F

RoHS compliant & Halogen free



SCOPE

This specification describes X5R series chip capacitors with lead-free terminations.

APPLICATIONS

PCs, Hard disk, Game PCs
Power supplies
DVD players
Mobile phones
Data processing

FEATURES

Supplied in tape on reel
Nickel-barrier end termination
RoHS compliant
Halogen free compliant

ORDERING INFORMATION – GLOBAL PART NUMBER, PHYCOMP CTC & 12NC

All part numbers are identified by the series, size, tolerance, TC material, packing style, voltage, process code, termination and capacitance value.

YAGEO BRAND ordering code**GLOBAL PART NUMBER (PREFERRED)**

CC XXXX X X **X5R** X **BB** XXX
(1) (2) (3) (4) (5)

(1) SIZE – INCH BASED (METRIC)

0201 (0603)
0402 (1005)
0603 (1608)
0805 (2012)
1206 (3216)
1210 (3225)
1812 (4532)

(2) TOLERANCE

K = $\pm 10\%$
M = $\pm 20\%$

(3) PACKING STYLE

R = Paper/PE taping reel; Reel 7 inch
K = Blister taping reel; Reel 7 inch
P = Paper/PE taping reel; Reel 13 inch
F = Blister taping reel; Reel 13 inch
C = Bulk case

(4) RATED VOLTAGE

4 = 4 V
5 = 6.3 V
6 = 10 V
7 = 16 V
8 = 25 V
9 = 50 V

(5) CAPACITANCE VALUE

2 significant digits+number of zeros
The 3rd digit signifies the multiplying factor, and letter R is decimal point
Example: 103 = $10 \times 10^3 = 10,000 \text{ pF} = 10 \text{ nF}$

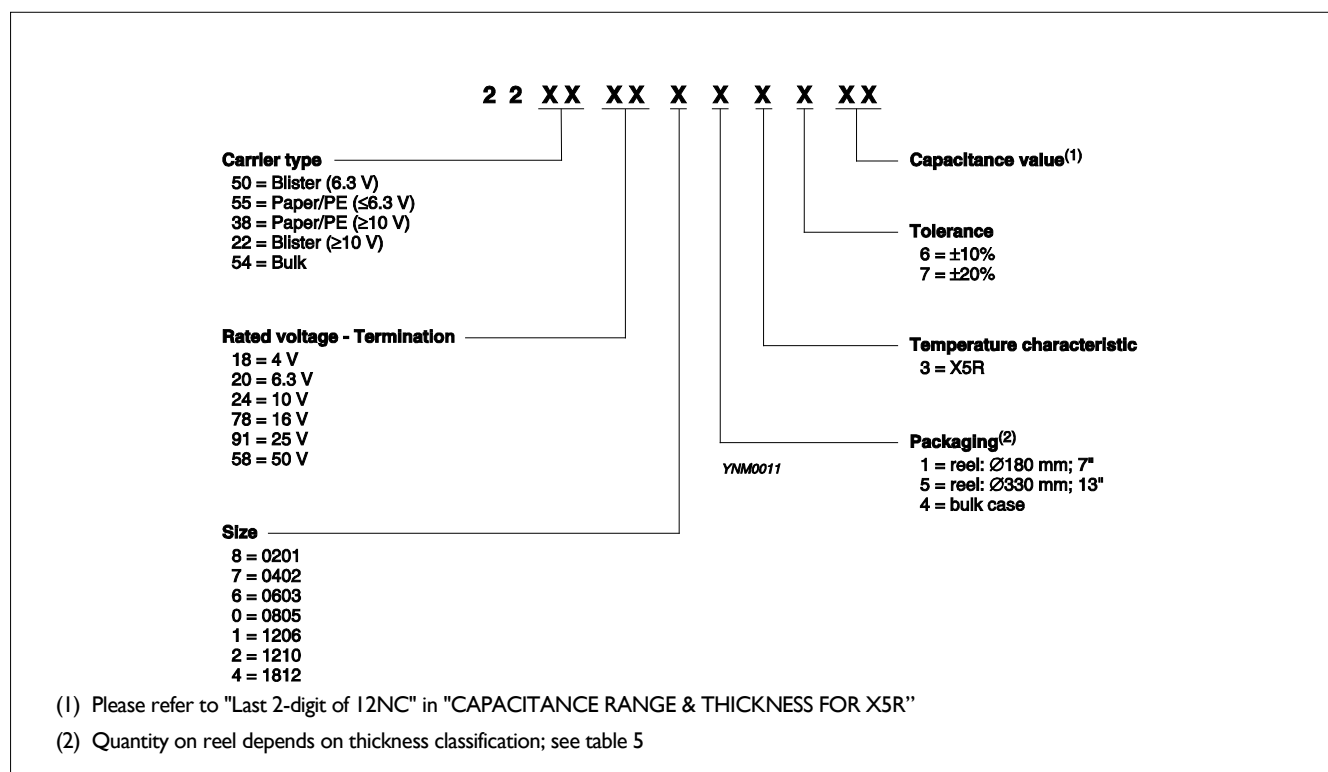
PHYCOMP BRAND ordering codes

GLOBAL PART NUMBER (preferred), PHYCOMP CTC (for North America) and I2NC (traditional) codes are acceptable to order Phycomp brand products.

GLOBAL PART NUMBER (PREFERRED)

For detailed information of GLOBAL PART NUMBER and ordering example, please refer to page 2.

I2NC CODE



PHYCOMP CTC CODE (FOR NORTH AMERICA)

Example: 06032B225M5B20D

0603	2B	225	M	5	B	2	0	D
Size code	Temp. Char.	Capacitance in pF	Tolerance	Voltage	Termination	Packing	Marking	Range identifier
0201	2B = X5R	101 = 100 pF; the	K = $\pm 10\%$ M = $\pm 20\%$	4 = 4 V	B = NiSn	2 = 180 mm	0 = no marking	D = Class 2 MLCC
0402		third digit signifies		5 = 6.3 V		7" Paper/PE		
0603		the multiplying		6 = 10 V		3 = 330 mm		
0805		factor:		7 = 16 V		13" Paper/PE		
1206		0 = $\times 1$		8 = 25 V		B = 180 mm		
1210		1 = $\times 10$		9 = 50 V		7" Blister		
1812		2 = $\times 100$				F = 330 mm		
		3 = $\times 1,000$				13" Blister		
		4 = $\times 10,000$				P = Bulk case		
		5 = $\times 100,000$						
		6 = $\times 1,000,000$						
		7 = $\times 10,000,000$						

CONSTRUCTION

The capacitor consists of a rectangular block of ceramic dielectric in which a number of interleaved metal electrodes are contained. This structure gives rise to a high capacitance per unit volume.

The inner electrodes are connected to the two end terminations and finally covered with a layer of plated tin (NiSn). The terminations are lead-free. A cross section of the structure is shown in Fig. 1.

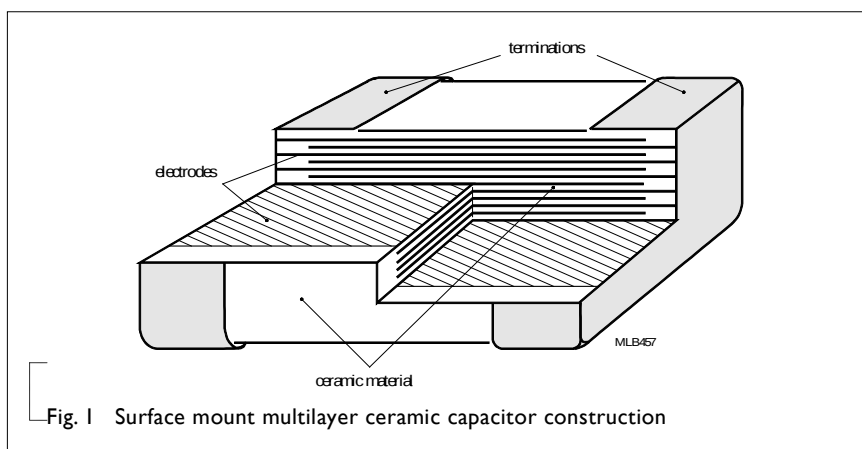


Fig. 1 Surface mount multilayer ceramic capacitor construction

DIMENSION

Table I For outlines see fig. 2

TYPE	L ₁ (mm)	W (mm)	T (MM)	L ₂ / L ₃ (mm)		L ₄ (mm)
				min.	max.	min.
0201	0.6 ±0.03 ⁽¹⁾	0.3 ±0.03 ⁽¹⁾	Refer to table 2 to 4	0.10	0.20	0.20
	0.6 ±0.05 ⁽²⁾	0.3 ±0.05 ⁽²⁾				
0402	1.0 ±0.05 ⁽¹⁾	0.5 ±0.05 ⁽¹⁾		0.20	0.30	0.40
	1.0 ±0.15 ⁽²⁾	0.5 ±0.15 ⁽²⁾				
	1.0 ±0.20 ⁽³⁾	0.5 ±0.20 ⁽³⁾				
0603	1.6 ±0.10 ⁽¹⁾	0.8 ±0.10 ⁽¹⁾		0.20	0.60	0.40
	1.6 ±0.15 ⁽²⁾	0.8 ±0.15 ⁽²⁾				
	1.6 ±0.20 ⁽³⁾	0.8 ±0.20 ⁽³⁾				
0805	2.0 ±0.10 ⁽¹⁾	1.25 ±0.10 ⁽¹⁾		0.25	0.75	0.55
	2.0 ±0.20 ⁽²⁾	1.25 ±0.20 ⁽²⁾				
	3.2 ±0.15 ⁽¹⁾	1.6 ±0.15 ⁽¹⁾				
1206	3.2 ±0.30 ⁽²⁾	1.6 ±0.20 ⁽²⁾		0.25	0.75	1.40
	3.2 ±0.30 ⁽³⁾	1.6 ±0.30 ⁽³⁾				
	3.2 ±0.20 ⁽¹⁾	2.5 ±0.20 ⁽¹⁾		0.25	0.75	1.40
1210	3.2 ±0.40 ⁽²⁾	2.5 ±0.30 ⁽²⁾				
1812	4.5 ±0.20 ⁽¹⁾	3.2 ±0.20 ⁽¹⁾		0.25	0.75	2.20
	4.5 ±0.40 ⁽²⁾	3.2 ±0.40 ⁽²⁾				

NOTE

- Dimensions for size 0201, C < 1 µF; 0402, C < 4.7 µF; 0603, C < 4.7 µF; 0805 to 1812, C ≤ 100 nF
- Dimensions for size 0201, C ≥ 100 nF (25V), C ≥ 1 µF; 0402, C ≥ 4.7 µF, C=2.2µF (16V); 0603, 10µF (6.3V) ≥ C ≥ 4.7µF, C ≥ 2.2µF (25V); 0805 to 1812, C > 100 nF
- Dimensions for size 0402, C ≥ 10 µF; 0603, C ≥ 10µF (≥10V), C=22µF(6.3V); 1206, C ≥ 22µF (25V), C ≥ 100µF

OUTLINES

For dimension see Table I

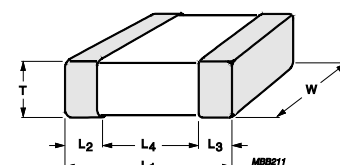


Fig. 2 Surface mount multilayer ceramic capacitor dimension

CAPACITANCE RANGE & THICKNESS FOR X5R

Table 2 Sizes from 0201 to 0402

CAP.	Last 2-digit of 12NC	0201 4 V	6.3 V	10 V	16 V	25 V	50 V	0402 4 V	6.3 V	10 V	16 V	25 V	50 V
100 pF	09												
150 pF	12												
220 pF	14												
330 pF	16						0.3±0.03						
470 pF	18												
680 pF	21												
1.0 nF	23					0.3±0.03							
1.5 nF	25												
2.2 nF	27												
3.3 nF	29		0.3±0.03	0.3±0.03	0.3±0.03								
4.7 nF	32												
6.8 nF	34												
10 nF	36												
15 nF	39												
22 nF	41												
33 nF	43												
47 nF	45												
68 nF	47										0.5±0.05	0.5±0.05	0.5±0.05
100 nF	49					0.3±0.05							
150 nF	52												
220 nF	54	0.3±0.03	0.3±0.03	0.3±0.03				0.5±0.05	0.5±0.05				
330 nF	56												
470 nF	58	0.3±0.03	0.3±0.03								0.5±0.05	0.5±0.05	0.5±0.05
680 nF	61												
1.0 µF	63	0.3±0.05	0.3±0.05								0.5±0.05	0.5±0.05	
2.2 µF	67										0.5±0.15		
4.7 µF	72						0.5±0.15	0.5±0.15	0.5±0.15				
10 µF	76						0.5±0.20	0.5±0.20					

NOTE

- Values in shaded cells indicate thickness class in mm
- Capacitance value of non E-6 series is available on request

CAPACITANCE RANGE & THICKNESS FOR X5R

Table 3 Sizes from 0603 to 0805

CAP.	Last 2-digit of I2NC	0603 6.3 V	10 V	16 V	25 V	50V	0805 6.3 V	10 V	16 V	25 V	50V
10 nF	36										
15 nF	38										
22 nF	41										
33 nF	43										
47 nF	45										
68 nF	47										
100 nF	49										
150 nF	52										
220 nF	54										
330 nF	56										
470 nF	58				0.8±0.1	0.8±0.1					
680 nF	61	0.8±0.1	0.8±0.1						0.85±0.1 1.25±0.2	1.25±0.2	1.25±0.2
1.0 µF	63						0.85±0.1 1.25±0.2	0.85±0.1 1.25±0.2		0.85±0.1 1.25±0.2	
2.2 µF	67				0.8±0.15						
4.7 µF	72			0.8±0.15							
10 µF	76	0.8±0.15		0.8±0.2	0.8±0.20				1.25±0.2	1.25±0.2	
22 µF	81	0.8±0.2	0.8±0.2				1.25±0.2	1.25±0.2			
47 µF	85										
100 µF	89										

NOTE

1. Values in shaded cells indicate thickness class in mm
2. Capacitance value of non E-6 series is available on request

Table 4 Sizes from I206 to I812

CAP.	Last 2-digit of I2NC	I206					I210					I812	
		6.3 V	10 V	16 V	25 V	50V	6.3 V	10 V	16 V	25 V	50V	6.3 V	
10 nF	36												
15 nF	38												
22 nF	41												
33 nF	43												
47 nF	45												
68 nF	47												
100 nF	49												
150 nF	52												
220 nF	54												
330 nF	56												
470 nF	58												
680 nF	61												
1.0 μ F	63						1.25 $\pm$ 0.2	1.25 $\pm$ 0.2	1.25 $\pm$ 0.2	1.25 $\pm$ 0.2	1.25 $\pm$ 0.2		
2.2 μ F	67	1.15 $\pm$ 0.1	1.15 $\pm$ 0.1	1.15 $\pm$ 0.1	1.15 $\pm$ 0.1	1.6 $\pm$ 0.2					1.9 $\pm$ 0.2		
4.7 μ F	72				1.6 $\pm$ 0.2	1.6 $\pm$ 0.2	1.9 $\pm$ 0.2	1.9 $\pm$ 0.2	1.9 $\pm$ 0.2	1.9 $\pm$ 0.2	2.5 $\pm$ 0.2		
10 μ F	76			1.6 $\pm$ 0.2		1.6 $\pm$ 0.3							
22 μ F	81	1.6 $\pm$ 0.2	1.6 $\pm$ 0.2		1.6 $\pm$ 0.3		2.5 $\pm$ 0.2	2.5 $\pm$ 0.2	2.5 $\pm$ 0.2	2.5 $\pm$ 0.3			
47 μ F	85											2.5 $\pm$ 0.2	
100 μ F	89	1.6 $\pm$ 0.3					2.5 $\pm$ 0.3	2.5 $\pm$ 0.3	2.5 $\pm$ 0.3			3.2 $\pm$ 0.3	

NOTE

1. Values in shaded cells indicate thickness class in mm
2. Capacitance value of non E-6 series is available on request

THICKNESS CLASSES AND PACKING QUANTITY

Table 5

SIZE CODE	THICKNESS CLASSIFICATION	TAPE WIDTH QUANTITY PER REEL	Ø180 MM / 7 INCH		Ø330 MM / 13 INCH		QUANTITY PER BULK CASE
			Paper	Blister	Paper	Blister	
0201	0.3 ±0.03 mm	8 mm	15,000	---	50,000	---	---
0402	0.5 ±0.05 mm	8 mm	10,000	---	50,000	---	50,000
0603	0.8 ±0.1 mm	8 mm	4,000	---	15,000	---	15,000
0805	0.6 ±0.1 mm	8 mm	4,000	---	20,000	---	10,000
	0.85 ±0.1 mm	8 mm	4,000	---	15,000	---	8,000
	1.25 ±0.2 mm	8 mm	---	3,000	---	10,000	5,000
1206	0.6 ±0.1 mm	8 mm	4,000	---	20,000	---	---
	0.85 ±0.1 mm	8 mm	4,000	---	15,000	---	---
	1.00 / 1.15 ±0.1 mm	8 mm	---	3,000	---	10,000	---
	1.25 ±0.2 mm	8 mm	---	3,000	---	10,000	---
	1.6 ±0.15 mm	8 mm	---	2,500	---	10,000	---
	1.6 ±0.2 mm	8 mm	---	2,000	---	8,000	---
1210	0.6 / 0.7 ±0.1 mm	8 mm	---	4,000	---	15,000	---
	0.85 ±0.1 mm	8 mm	---	4,000	---	10,000	---
	1.15 ±0.1 mm	8 mm	---	3,000	---	10,000	---
	1.15 ±0.15 mm	8 mm	---	3,000	---	10,000	---
	1.25 ±0.2 mm	8 mm	---	3,000	---	---	---
	1.5 ±0.1 mm	8 mm	---	2,000	---	---	---
	1.6 / 1.9 ±0.2 mm	8 mm	---	2,000	---	---	---
	2.0 ±0.2 mm	8 mm	---	2,000 1,000	---	---	---
1808	2.5 ±0.2 mm	8 mm	---	1,000 500	---	---	---
	1.15 ±0.15 mm	12 mm	---	3,000	---	---	---
	1.25 ±0.2 mm	12 mm	---	3,000	---	---	---
	1.35 ±0.15 mm	12 mm	---	2,000	---	---	---
	1.5 ±0.1 mm	12 mm	---	2,000	---	---	---
	1.6 ±0.2 mm	12 mm	---	2,000	---	---	---
1812	2.0 ±0.2 mm	12 mm	---	2,000	---	---	---
	0.6 / 0.85 ±0.1 mm	12 mm	---	2,000	---	---	---
	1.15 ±0.1 mm	12 mm	---	1,000	---	---	---
	1.25 ±0.2 mm	12 mm	---	1,000	---	---	---
	1.5 ±0.1 mm	12 mm	---	1,000	---	---	---
	1.6 ±0.2 mm	12 mm	---	1,000	---	---	---
	2.0 ±0.2 mm	12 mm	---	1,000	---	---	---
	2.5 ±0.2 mm	12 mm	---	500	---	---	---

ELECTRICAL CHARACTERISTICS**X5R DIELECTRIC CAPACITORS; NISN TERMINATIONS**

Unless otherwise specified, all tests and measurements shall be made under standard atmospheric conditions for testing as given in 5.3 of IEC 60068-1:

- Temperature: 15 °C to 35 °C
- Relative humidity: 25% to 75%
- Air pressure: 86 kPa to 106 kPa

Before the measurements are made, the capacitor shall be stored at the measuring temperature for a time sufficient to allow the entire capacitor to reach this temperature.

The period as prescribed for recovery at the end of a test is normally sufficient for this purpose.

Table 6

DESCRIPTION	VALUE
Capacitance range	10 nF to 100 μ F
Capacitance tolerance	$\pm 10\%$ and $\pm 20\%$
Dissipation factor (D.F.)	
6.3 V	$\leq 5\%$
Exception:	0402 ≥ 180 nF; 1210 ≥ 22 μ F $\leq 7\%$
	0201 ≥ 12 nF; 0402 ≥ 330 nF; 0603 ≥ 2.2 μ F; $\leq 10\%$
	0805 ≥ 1 μ F; 1206 ≥ 22 μ F; 1210 ≥ 47 μ F
	1206 ≥ 100 μ F $\leq 15\%$
10 V	$\leq 5\%$
Exception:	0402 ≥ 180 nF; 0805 ≥ 1 μ F; 1206 ≥ 6.8 μ F $\leq 7\%$
	0201 ≥ 12 nF; 0402 ≥ 330 nF; 0603 ≥ 1 μ F; $\leq 10\%$
	0805 ≥ 2.2 μ F; 1206 ≥ 10 μ F; 1210 ≥ 10 μ F
16 V	$\leq 5\%$
Exception:	0402 ≥ 180 nF; 0603 ≥ 680 nF; 0805 ≥ 1 μ F $\leq 7\%$
	0201 ≥ 100 nF; 0402 ≥ 330 nF; 0603 ≥ 2.2 μ F; $\leq 10\%$
	0805 ≥ 4.7 μ F; 1206 ≥ 10 μ F; 1210 ≥ 10 μ F
25 V	$\leq 3.5\%$
Exception:	0402 ≥ 27 nF; 0603 ≥ 220 nF; 0805 ≥ 2.2 μ F; $\leq 5\%$
	1206 ≥ 4.7 μ F; 1210 ≥ 10 μ F
	0402 ≥ 180 nF $\leq 7\%$
	0402 ≥ 470 nF; 0603 ≥ 2.2 μ F; 0805 ≥ 4.7 μ F; $\leq 10\%$
	1206 ≥ 10 μ F; 1210 ≥ 22 μ F
50V	$\leq 3.5\%$
Exception:	0402 ≥ 27 nF; $\leq 5\%$
	0402 ≥ 180 nF; $\leq 7\%$
	0402 $\geq$ 470nF; 0603 ≥ 220 nF; 0805 ≥ 470 nF; $\leq 10\%$
	1206 ≥ 1 μ F; 1210 ≥ 1 μ F

DESCRIPTION	VALUE
	$R_{ins} \geq 10\text{ G}\Omega$ or $R_{ins} \times C_r \geq 500\text{ (100/50) seconds}$ whichever is less
Insulation resistance after 1 minute at U_r (DC)	$R_{ins} \times C_r \geq 100(50)\text{ seconds}$: 0201 $\geq 100\text{nF}$, 0402 $\geq 1\mu\text{F}$, 0603 $\geq 1\mu\text{F}$, 0805 $\geq 10\mu\text{F}$, 1206 $\geq 10\mu\text{F}$, 1210 $\geq 10\mu\text{F}$, 1812 $\geq 47\mu\text{F}$
Maximum capacitance change as a function of temperature (temperature characteristic/coefficient):	$\pm 15\%$
Operating temperature range:	$-55\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$

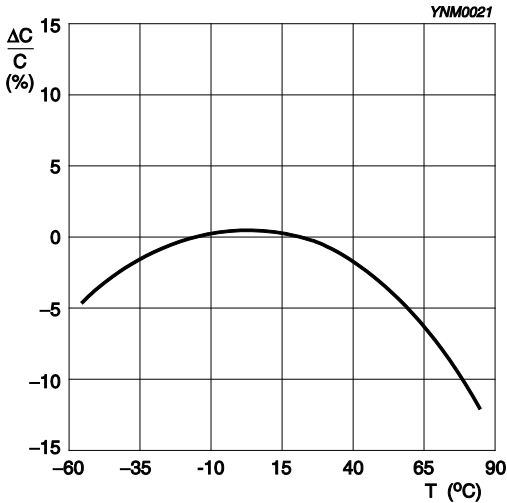


Fig. 3 Typical capacitance change as a function of temperature

Size 0201 10 nF / 16 V

Solid lines: Impedance / Dotted lines: ESR

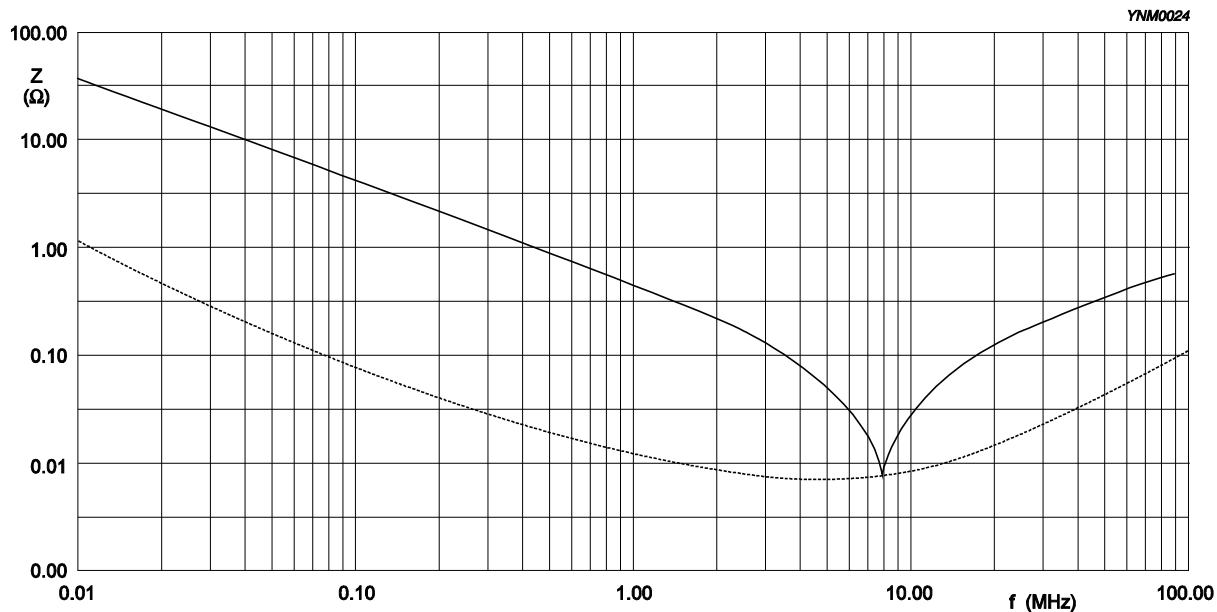


Fig. 4 Impedance ESR vs. frequency characteristics for multilayer chip capacitors

 Size 0603 1 μ F / 10 V

Solid lines: Impedance / Dotted lines: ESR

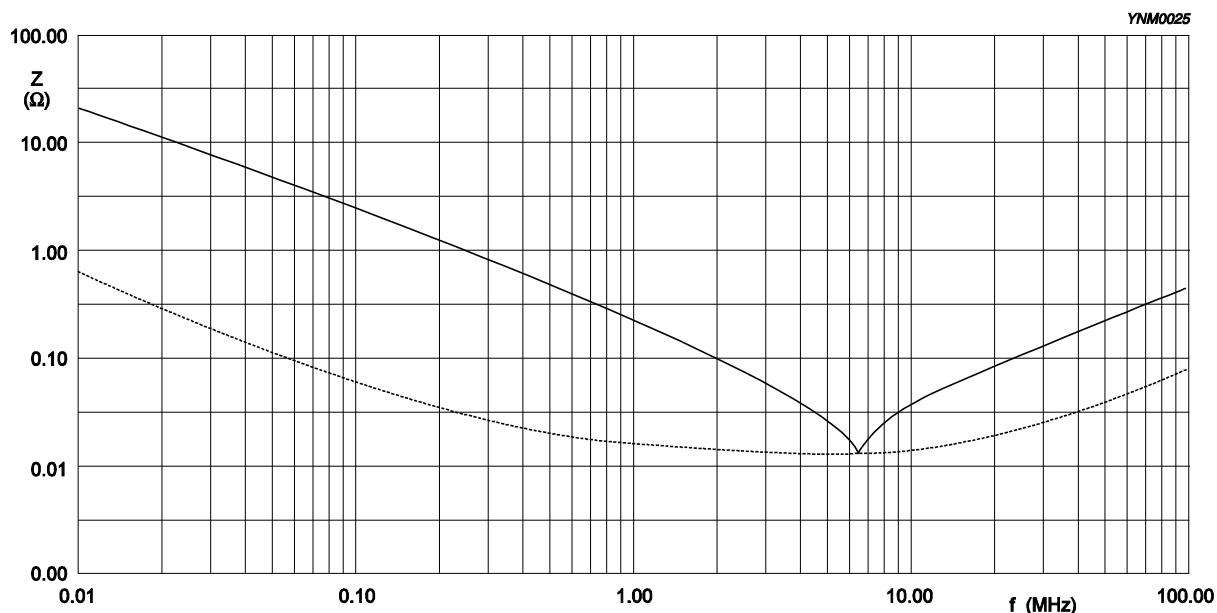


Fig. 5 Impedance ESR vs. frequency characteristics for multilayer chip capacitors

Size 0805 10 μ F / 6.3 V

Solid lines: Impedance / Dotted lines: ESR

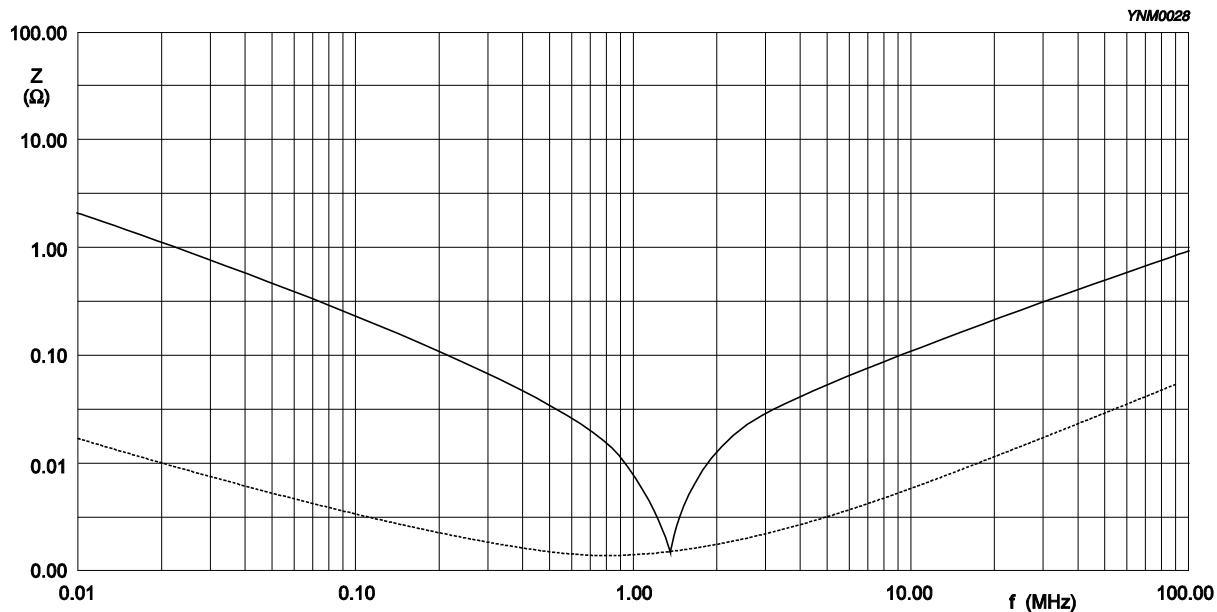


Fig. 6 Impedance ESR vs. frequency characteristics for multilayer chip capacitors

 Size 1206 10 μ F / 16 V

Solid lines: Impedance / Dotted lines: ESR

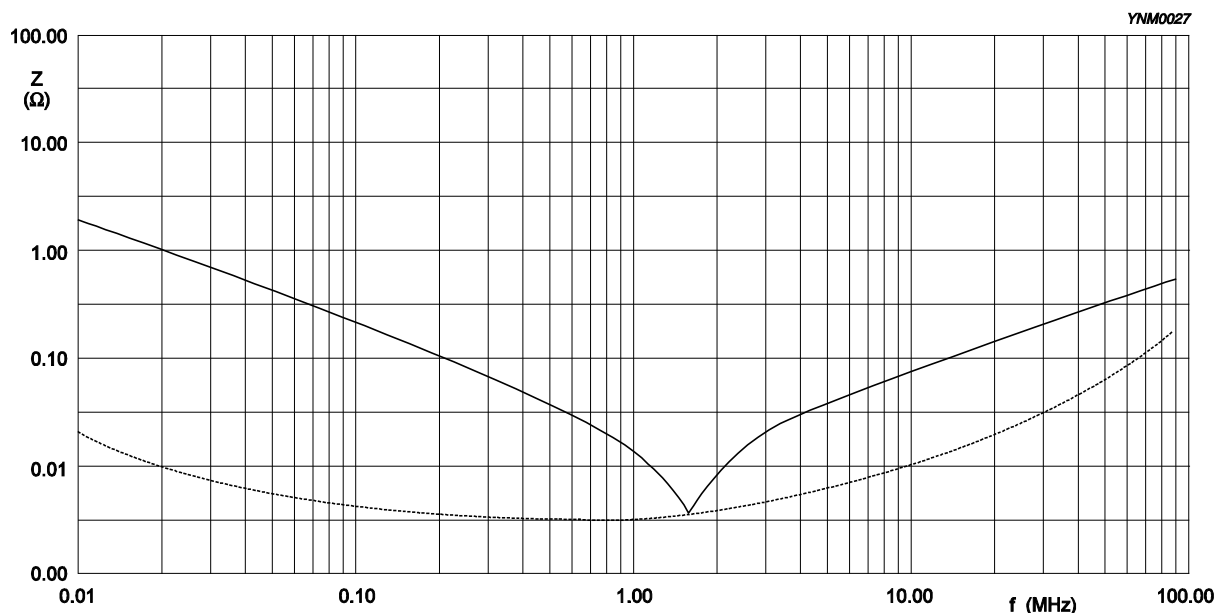


Fig. 7 Impedance ESR vs. frequency characteristics for multilayer chip capacitors

Size 1210 10 μ F / 25 V
Solid lines: Impedance / Dotted lines: ESR

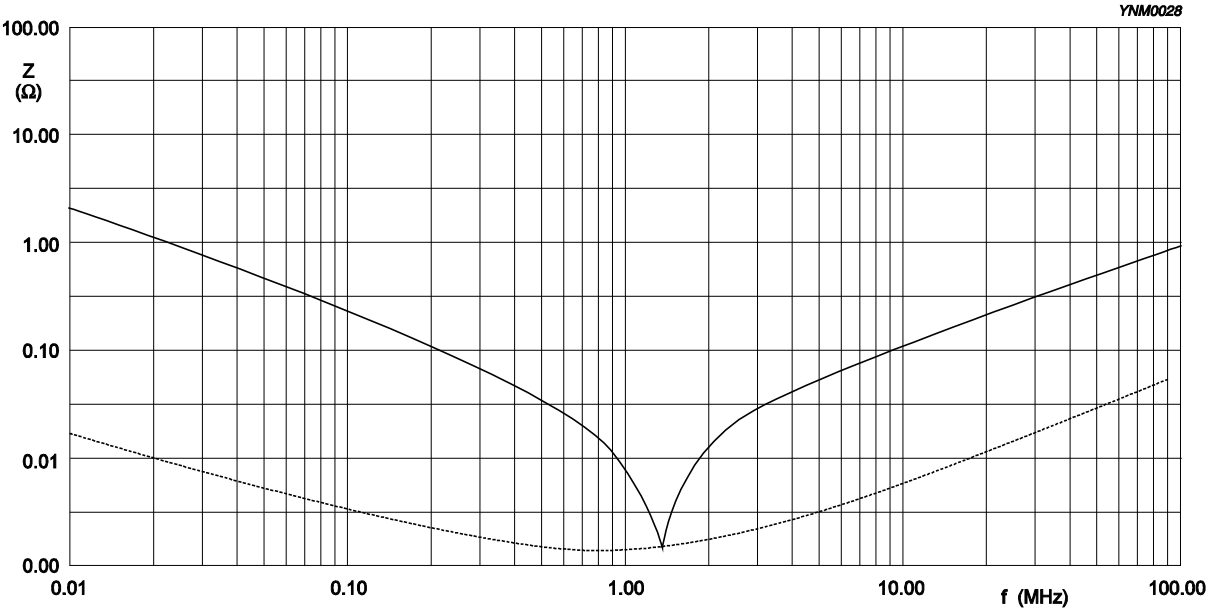


Fig. 8 Impedance ESR vs. frequency characteristics for multilayer chip capacitors

SOLDERING RECOMMENDATION

Table 7

SOLDERING METHOD	SIZE 0402	0603	0805	1206	≥ 1210
Reflow	≥ 0.1 μ F	≥ 1.0 μ F	≥ 2.2 μ F	≥ 4.7 μ F	Reflow only
Reflow/Wave	< 0.1 μ F	< 1.0 μ F	< 2.2 μ F	< 4.7 μ F	---

TESTS AND REQUIREMENTS

Table 8 Test procedures and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Mounting	IEC 60384-21/22 4.3	The capacitors may be mounted on printed-circuit boards or ceramic substrates	No visible damage
Visual Inspection and Dimension Check	4.4	Any applicable method using $\times 10$ magnification	In accordance with specification
Capacitance ⁽¹⁾	4.5.1	Class 2: At 20 °C, 24 hrs after annealing $f = 1 \text{ KHz}$ for $C \leq 10 \mu\text{F}$, rated voltage $> 6.3 \text{ V}$, measuring at voltage $1 V_{\text{rms}}$ at 20 °C $f = 1 \text{ KHz}$, for $C \leq 10 \mu\text{F}$, rated voltage $\leq 6.3 \text{ V}$, measuring at voltage $0.5 V_{\text{rms}}$ at 20 °C $f = 120 \text{ Hz}$ for $C > 10 \mu\text{F}$, measuring at voltage $0.5 V_{\text{rms}}$ at 20 °C	Within specified tolerance
Dissipation Factor (D.F.) ⁽¹⁾	4.5.2	Class 2: At 20 °C, 24 hrs after annealing $f = 1 \text{ KHz}$ for $C \leq 10 \mu\text{F}$, rated voltage $> 6.3 \text{ V}$, measuring at voltage $1 V_{\text{rms}}$ at 20 °C $f = 1 \text{ KHz}$, for $C \leq 10 \mu\text{F}$, rated voltage $\leq 6.3 \text{ V}$, measuring at voltage $0.5 V_{\text{rms}}$ at 20 °C $f = 120 \text{ Hz}$ for $C > 10 \mu\text{F}$, measuring at voltage $0.5 V_{\text{rms}}$ at 20 °C	In accordance with specification
Insulation Resistance	4.5.3	At U_r (DC) for 1 minute	In accordance with specification

NOTE

1. The figure indicates typical inspection. Please refer to individual specifications.

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS												
Temperature Characteristic	4.6	Capacitance shall be measured by the steps shown in the following table. The capacitance change should be measured after 5 min at each specified temperature stage. <table><tr><th>Step</th><th>Temperature(°C)</th></tr><tr><td>a</td><td>25±2</td></tr><tr><td>b</td><td>Lower temperature±3°C</td></tr><tr><td>c</td><td>25±2</td></tr><tr><td>d</td><td>Upper Temperature±2°C</td></tr><tr><td>e</td><td>25±2</td></tr></table> (1) Class I Temperature Coefficient shall be calculated from the formula as below Temp, Coefficient = $\frac{C2 - C1}{C1 \times \Delta T} \times 10^6$ [ppm/°C] C1: Capacitance at step c C2: Capacitance at 125°C ΔT: 100°C(=125°C-25°C) (2) Class II Capacitance Change shall be calculated from the formula as below ΔC = $\frac{C2 - C1}{C1} \times 100\%$ C1: Capacitance at step c C2: Capacitance at step b or d	Step	Temperature(°C)	a	25±2	b	Lower temperature±3°C	c	25±2	d	Upper Temperature±2°C	e	25±2	<General purpose series> Class I: Δ C/C: ±30ppm Class2: X7R: Δ C/C: ±15% Y5V: Δ C/C: 22~-82% <High Capacitance series> Class2: X7R/X5R: Δ C/C: ±15% Y5V: Δ C/C: 22~-82%
Step	Temperature(°C)														
a	25±2														
b	Lower temperature±3°C														
c	25±2														
d	Upper Temperature±2°C														
e	25±2														
Adhesion	4.7	A force applied for 10 seconds to the line joining the terminations and in a plane parallel to the substrate	Force size ≥ 0603: 5N size = 0402: 2.5N size = 0201: 1N												
Bending Strength	IEC 60384-21/22 4.8	Mounting in accordance with IEC 60384-22 paragraph 4.3 Conditions: bending 1 mm at a rate of 1 mm/s, radius jig 340 mm	No visible damage <General purpose series> ΔC/C Class2: X5R: ±10% <High Capacitance series> ΔC/C Class2: X5R: ±10%												

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Resistance to Soldering Heat	4.9	Precondition: 150 +0/-10 °C for 1 hour, then keep for 24 ±1 hours at room temperature Preheating: for size ≤ 1206: 120 °C to 150 °C for 1 minute Preheating: for size >1206: 100 °C to 120 °C for 1 minute and 170 °C to 200 °C for 1 minute Solder bath temperature: 260 ±5 °C Dipping time: 10 ±0.5 seconds Recovery time: 24 ±2 hours	Dissolution of the end face plating shall not exceed 25% of the length of the edge concerned <General purpose series> $\Delta C/C$ Class2: X5R: ±10% <High Capacitance series> $\Delta C/C$ Class2: X5R: ±10% D.F. within initial specified value R_{ins} within initial specified value
Solderability	4.10	Preheated the temperature of 80 °C to 140 °C and maintained for 30 seconds to 60 seconds. 1. Temperature: 235±5°C / Dipping time: 2 ±0.5 s 2. Temperature: 245±5°C / Dipping time: 3 ±0.5 s (lead free) Depth of immersion: 10mm	The solder should cover over 95% of the critical area of each termination
Rapid Change of Temperature	IEC 60384-21/22 4.11	Preconditioning: 150 +0/-10 °C for 1 hour, then keep for 24 ±1 hours at room temperature 5 cycles with following detail: 30 minutes at lower category temperature 30 minutes at upper category temperature Recovery time 24 ±2 hours	No visual damage <General purpose series> $\Delta C/C$ Class2: X5R: ±15% <High Capacitance series> $\Delta C/C$ Class2: X5R: ±15% D.F. meet initial specified value R_{ins} meet initial specified value

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Damp Heat with U_r Load	4.13	1. Preconditioning, class 2 only: 150 $\pm$ 10 $^{\circ}$C / 1 hour, then keep for 24 $\pm$ 1 hour at room temp 2. Initial measure: Spec: refer to initial spec C, D, IR 3. Damp heat test: 500 $\pm$ 12 hours at 40 $\pm$ 2 $^{\circ}$C; 90 to 95% R.H. 1.0 U_r applied 4. Recovery: Class 2: 24 $\pm$ 2 hours 5. Final measure: C, D, IR P.S. If the capacitance value is less than the minimum value permitted, then after the other measurements have been made the capacitor shall be preconditioned according to "IEC 60384 4.1" and then the requirements shall be met.	No visual damage after recovery <General purpose series> $\Delta C/C$ Class2: X5R: $\pm$ 15% D.F. Class2: X5R: $\leq$ 16V: $\leq$ 7% $\geq$ 25V: $\leq$ 5% R_{ins} Class2: X5R: $\geq$ 500 MΩ or $R_{ins} \times C_r \geq 25s$ whichever is less <High Capacitance series> $\Delta C/C$ Class2: X5R: $\pm$ 20% D.F. Class2: X5R: 2 x initial value max R_{ins} Class2: $R_{ins} \times C_r \geq 5s$ whichever is less

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Endurance	IEC 60384-21/22 4.14	1. Preconditioning, class 2 only: 150 +0/-10 °C /1 hour, then keep for 24 ±1 hour at room temp 2. Initial measure: Spec: refer to initial spec C, D, IR 3. Endurance test: Temperature: X5R: 85 °C Specified stress voltage applied for 1,000 hours: Applied 2.0 × Ur for general product. Applied 1.5 × Ur for high cap. product. Applied 1.0 × Ur for high cap. product. 0201: 100nF/25V, 220nF/10V, 1uF/6.3V; 0402: 4.7uF/10V, 6.3V, 10uF/4V, 6.3V; 0603: 10uF/ 10V, 22uF/6.3V, 10V 1206: 10uF/ 50V 4. Recovery time: 24 ±2 hours 5. Final measure: C, D, IR P.S. If the capacitance value is less than the minimum value permitted, then after the other measurements have been made the capacitor shall be preconditioned according to "IEC 60384 4.1" and then the requirements shall be met.	No visual damage <General purpose series> ΔC/C Class2: X5R: ±15% D.F. Class2: X5R: ≤ 16V: ≤ 7% ≥ 25V: ≤ 5% R_{ins} Class2: X5R: ≥ 1,000 MΩ or R_{ins} × C_r ≥ 50s whichever is less <High Capacitance series> ΔC/C Class 2: X5R: ±20% D.F. Class 2: X5R: 2 × initial value max R_{ins} Class 2: R_{ins} × C_r ≥ 10s whichever is less
Voltage Proof		Specified stress voltage applied for 1 min Ur ≤ 50 V: series applied 2.5 Ur Charge/Discharge current less than 7.5mA	No breakdown or flashover

REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 19	Apr. 09, 2015	-	- Voltage updated
Version 18	Jul. 07, 2014	-	- Voltage updated
Version 17	Mar. 31, 2014	-	- Test condition updated
Version 16	Nov. 29, 2012	-	- Test condition updated
Version 15	Sep. 03, 2012	-	- Test condition updated
Version 14	May 16, 2012	-	- Product range updated
Version 13	May 02, 2012	-	- Product range updated
Version 12	Feb 10, 2012	-	- Product range updated
Version 11	Oct 21, 2011	-	- Product range updated
Version 10	Jun 21, 2011	-	- Product range updated
Version 9	Mar 23, 2011	-	- Product range updated
Version 8	Jan 25, 2011	-	- Rated voltage of 0201 extend to 50V
Version 7	Jan 05, 2011	-	- Product range updated
Version 6	Jul 27, 2010	-	- Dimension on 0603 and 1206 case size updated
Version 5	Apr 21, 2010	-	- The statement of "Halogen free" on the cover added - Dimension updated
Version 4	Jan 13, 2010	-	- Thickness updated
Version 3	Aug 17, 2009	-	- Dimension updated
Version 2	Jun 09, 2009	-	- Ordering code updated
Version 1	May 15, 2009	-	- Product range updated
Version 0	Apr 15, 2009	-	- New datasheet for general purpose and high capacitance X5R series with RoHS compliant - Replace the "6.3V to 50V" part of pdf files: UP-X5R_X7R_HighCaps_6.3-to-25V_11, UY-X5R_X7R_HighCaps_6.3-to-25V_11 - Combine 0201 from pdf files: UP-NP0X5RX7RY5V_0201_6.3-to-50V_2 and UY-NP0X5RX7RY5V_0201_6.3-to-50V_2 - Define global part number - Description of "Halogen free compliant" added - Test method and procedure updated



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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